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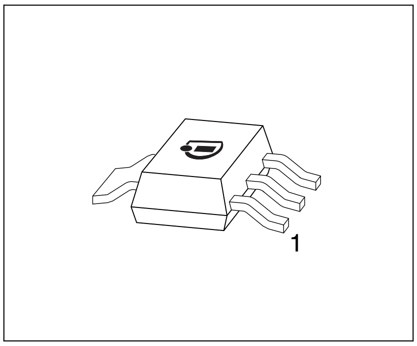
- High-side switch
- Short-circuit protection
- Input protection
- Overtemperature protection with hysteresis
- Overload protection
- Overvoltage protection
- Switching inductive load
- Clamp of negative output voltage with inductive loads
- Undervoltage shutdown
- Maximum current internally limited
- **E**lectro**s**tatic **d**ischarge (**ESD**) protection
- Reverse battery protection[1)]
- AEC qualified
- Green product (RoHS compliant)



PG-SOT-223

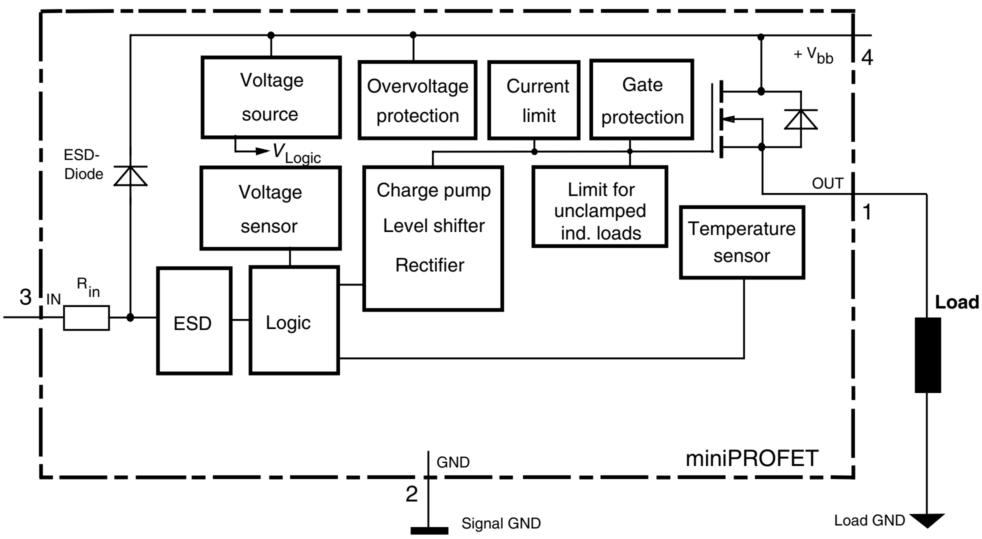
Application

- µC compatible power switch for 12 V DC grounded loads
- All types of resistive, inductive and capacitive loads
- Replaces electromechanical relays and discrete circuits

General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input,monolithically integrated in Smart SIPMOS® technology. Fully protected by embedded protection functions.

Blockdiagramm:



1) With resistor R_{GND}=150 Ω in GND connection, resistor in series with IN connections reverse load current limited by connected load.

Pin	Symbol		Function
1	OUT	O	Output to the load
2	GND	-	Logic ground
3	IN	I	Input, activates the power switch in case of logical high signal
4	Vbb	+	Positive power supply voltage

Maximum Ratings at T_j = 25 °C unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage	V_{bb}	40	V
Load current self-limited	I_L	$I_{L(SC)}$	A
Maximum input voltage[2]	V_{IN}	-5.0... V_{bb}	V
Maximum input current	I_{IN}	±5	mA
Inductive load switch-off energy dissipation, single pulse I_L = 0.5A , T_A = 150°C (not tested, specified by design)	E_{AS}	0.5	J
Load dump protection[3] $V_{LoadDump}=U_A+V_s$ R_I=2Ω , t_d=400ms, IN= low or high, U_A=13,5V R_L= 24Ω R_L= 80Ω (not tested, specified by design)	$V_{Load\ dump}$[4]	60 80	V
Electrostatic discharge capability (ESD)[5] PIN 3 PIN 1,2,4	V_{ESD}	±1 ±2	kV
Operating temperature range Storage temperature range	T_j T_{stg}	-40 ...+150 -55 ...+150	°C
Max. power dissipation (DC)[6] T_A = 25 °C	P_{tot}	1.8	W
Thermal resistance chip - soldering point: chip - ambient:[6]	R_{thJS} R_{thJA}	7 70	K/W

2) At $V_{IN} > V_{bb}$, the input current is not allowed to exceed ±5 mA.
3) Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND pin, e.g. with a 150 Ω resistor in the GND connection A resistor for the protection of the input is integrated.
4) $V_{Load\ dump}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839
5) HBM according to MIL-STD 883D, Methode 3015.7
6) BSP 452 on epoxy pcb 40 mm x 40 mm x 1.5 mm with 6 cm^2 copper area for V_{bb} connection

Electrical Characteristics

Parameter and Conditions at T_j = 25 °C, V_{bb} = 13.5V unless otherwise specified	Symbol	Values			Unit
		min	typ	max	
Load Switching Capabilities and Characteristics					
On-state resistance (pin 4 to 1) I_L = 0.5 A, V_{in} = high T_j = 25°C T_j = 150°C	R_{ON}	-- --	0.16 --	0.2 0.4	Ω
Nominal load current (pin 4 to 1)[7)] ISO Standard: V_{ON} = V_{bb} - V_{OUT} = 0.5 V T_S = 85 °C	$I_{L(ISO)}$	0.7	--	--	A
Turn-on time to 90% V_{OUT} Turn-off time to 10% V_{OUT} R_L = 24 Ω	t_{on} t_{off}	-- --	60 60	100 150	µs
Slew rate on 10 to 30% V_{OUT}, R_L = 24 Ω	dV/dt_{on}	--	2	4	V/µs
Slew rate off 70 to 40% V_{OUT}, R_L = 24 Ω	$-dV/dt_{off}$	--	2	4	V/µs

Input

Parameter and Conditions	Symbol	min	typ	max	Unit
Allowable input voltage range, (pin 3 to 2)	V_{IN}	-3.0	--	V_{bb}	V
Input turn-on threshold voltage T_j = -40...+150°C	$V_{IN(T+)}$	--	--	3.5	V
Input turn-off threshold voltage T_j = -40...+150°C	$V_{IN(T-)}$	1.5	--	--	V
Input threshold hysteresis	$\Delta V_{IN(T)}$	--	0.5	--	V
Off state input current (pin 3) $V_{IN(off)}$ = 1.2 V T_j = -40...+150°C	$I_{IN(off)}$	10	--	60	µA
On state input current (pin 3) $V_{IN(on)}$ = 3.0 V to V_{bb} T_j = -40...+150°C	$I_{IN(on)}$	10	--	100	µA
Input resistance	R_{IN}	1.5	2.8	3.5	kΩ

7) $I_{L(ISO)}$ is limited by current limitation, see $I_{L(SC)}$, next page

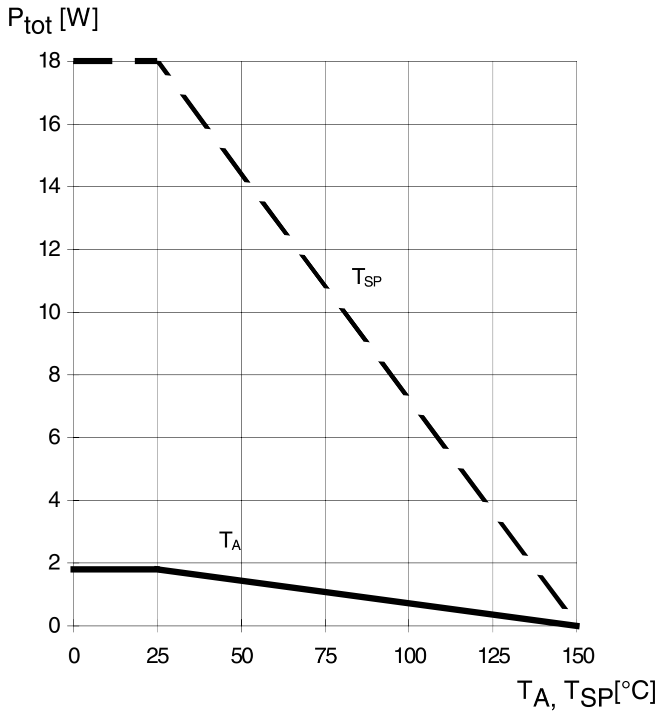
Parameter and Conditions at T_j = 25 °C, V_{bb} = 13.5V unless otherwise specified	**Symbol**	**Values** min	typ	max	**Unit**
Operating Parameters					
Operating voltage[8)] T_j =-40...+150°C	$V_{bb(on)}$	5.0	--	34	V
Undervoltage shutdown T_j =-40...+150°C	$V_{bb(under)}$	3.5	--	5	V
Undervoltage restart T_j =-40...+25°C T_j =+150°C	$V_{bb(u\ rst)}$	--	--	6.5 7.0	V
Undervoltage restart of charge pumpe see diagram page 7	$V_{bb(ucp)}$	--	5.6	7	V
Undervoltage hysteresis $\Delta V_{bb(under)} = V_{bb(u\ rst)} - V_{bb(under)}$	$\Delta V_{bb(under)}$	--	0.3	--	V
Overvoltage shutdown T_j =-40...+150°C	$V_{bb(over)}$	34	--	42	V
Overvoltage restart T_j =-40...+150°C	$V_{bb(o\ rst)}$	33	--	--	V
Overvoltage hysteresis T_j =-40...+150°C	$\Delta V_{bb(over)}$	--	0.7	--	V
Standby current (pin 4), V_{in} = low T_j =-40...+150°C	$I_{bb(off)}$	--	10	25	µA
Operating current (pin 2), V_{in} = 5 V	I_{GND}	--	1	1.6	mA
leakage current (pin 1) V_{in} = low T_j =-40...+25°C T_j =150°C	$I_{L(off)}$	--	2	5 7	µA
Protection Functions					
Current limit (pin 4 to 1) T_j = 25°C V_{bb} = 20V T_j = -40...+150°C	$I_{L(SC)}$	0.7 0.7	1.5 --	2 2.4	A
Overvoltage protection I_{bb}=4mA T_j =-40...+150°C	$V_{bb(AZ)}$	41	--	--	V
Output clamp (ind. load switch off) at $V_{OUT}=V_{bb}-V_{ON(CL)}$, I_{bb} = 4mA	$V_{ON(CL)}$	41	47	--	V
Thermal overload trip temperature	T_{jt}	150	--	--	°C
Thermal hysteresis	ΔT_{jt}	--	10	--	K
Inductive load switch-off energy dissipation[9)] $T_{j\ Start}$ = 150 °C, single pulse, I_L = 0.5 A, V_{bb} = 12 V (not tested, specified by design)	E_{AS}	--	--	0.5	J
Reverse battery (pin 4 to 2) [10)] (not tested, specified by design)	$-V_{bb}$	--	--	30	V

8) At supply voltage increase up to V_{bb}= 5.6 V typ without charge pump, $V_{OUT} \approx V_{bb}$ - 2 V

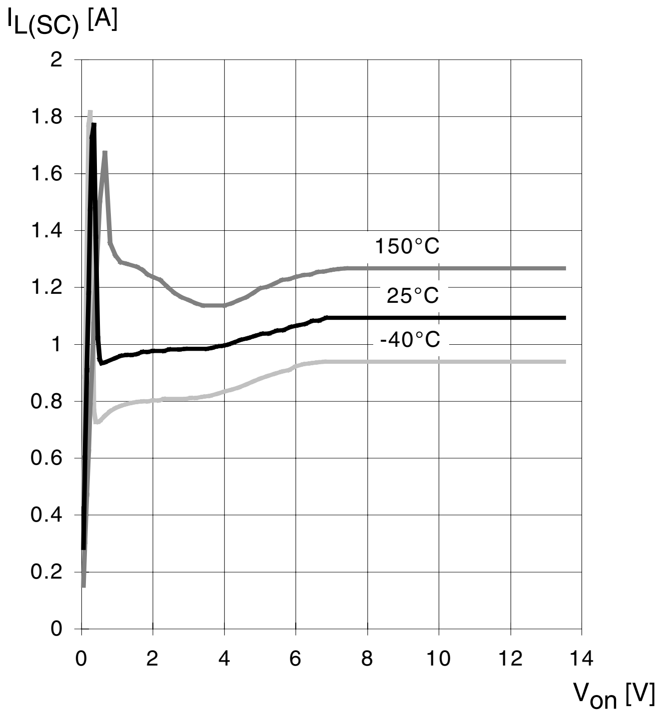
9) While demagnetizing load inductance, dissipated energy in PROFET is $E_{AS}= \int V_{ON(CL)} * i_L(t)\, dt$, approx.
$E_{AS}= {}^1/_2 * L * I_L^2 * (\frac{V_{ON(CL)}}{V_{ON(CL)} - V_{bb}})$

10) Requires 150 Ω resistor in GND connection. Reverse load current (through intrinsic drain-source diode) is normally limited by the connected load.

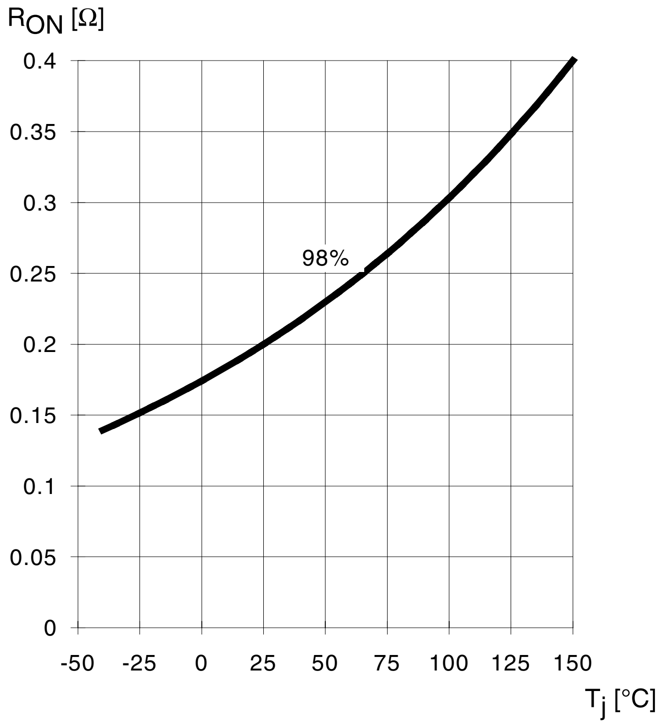
Max. allowable power dissipation
P_{tot} = f (T_A,T_{SP})



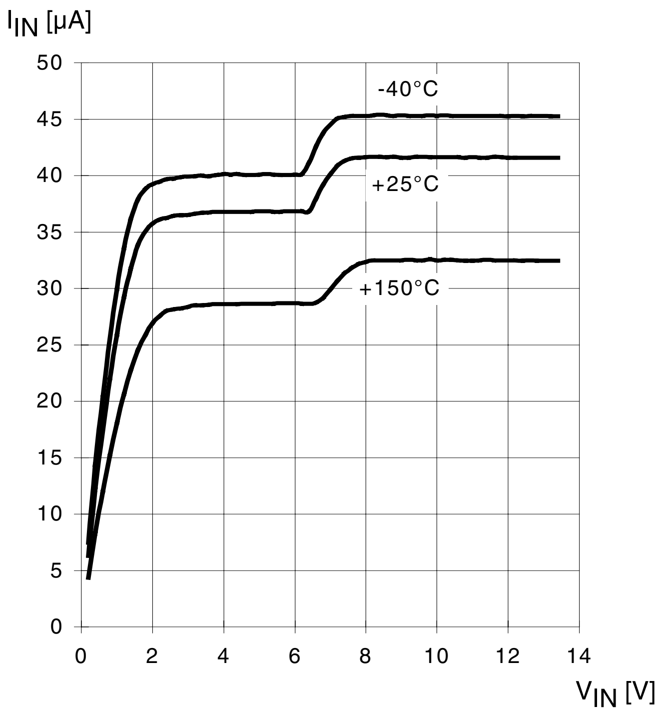
Current limit characteristic
$I_{L(SC)}$ = f (V_{on}); (V_{on} see testcircuit)



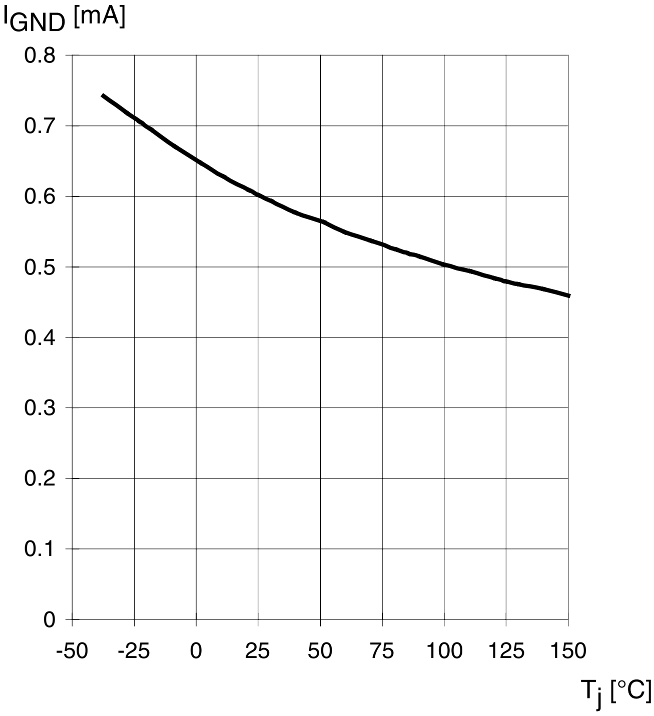
On state resistance (Vbb-pin to OUT-pin)
R_{ON} = f (Tj); V_{bb} = 13.5 V; I_L = 0.5 A



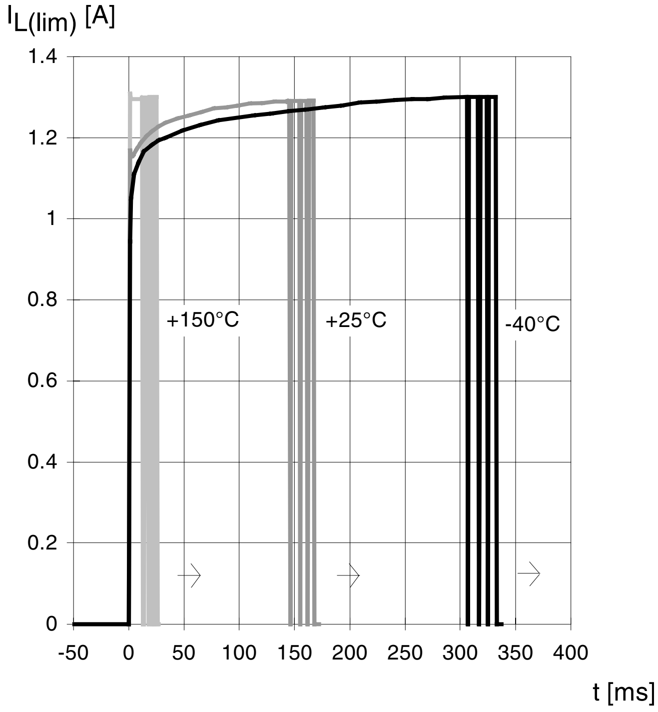
Typ. input current
I_{IN} = f (V_{IN}); V_{bb} = 13,5 V



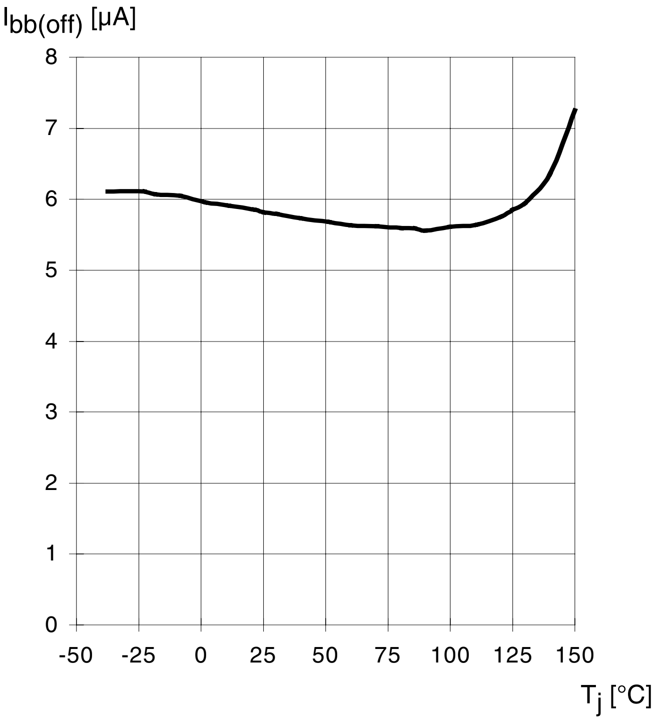
Typ. operating current
I_{GND} = f (T_j); V_{bb} = 13,5 V; V_{IN} = high



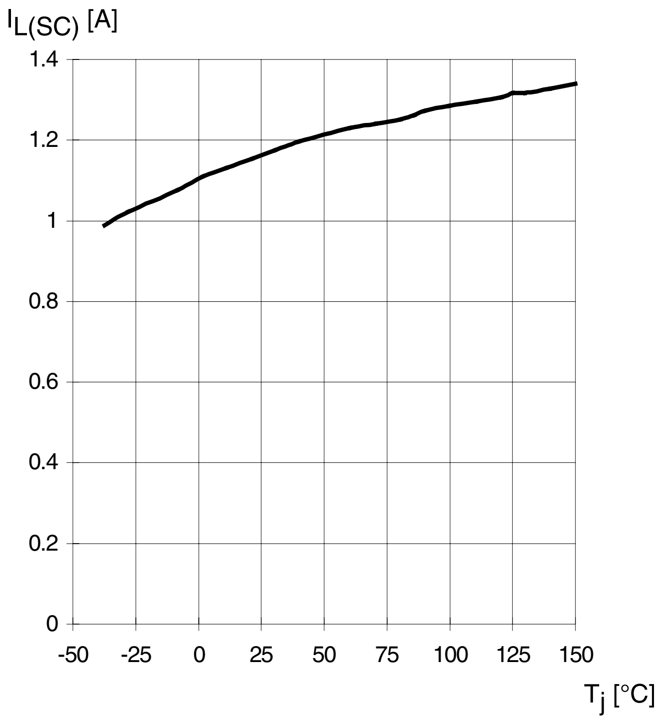
Typ. overload current
$I_{L(lim)}$ = f (t); V_{bb} = 13,5 V, no heatsink, Param.: T_{jstart}



Typ. standby current
$I_{bb(off)}$ = f (T_j); V_{bb} = 13,5 V; V_{IN} = low



Short circuit current
$I_{L(SC)}$ = f (T_j); V_{bb} = 13,5 V



Typ. input turn on voltage threshold
$V_{IN(T+)}$ = f (T_j);

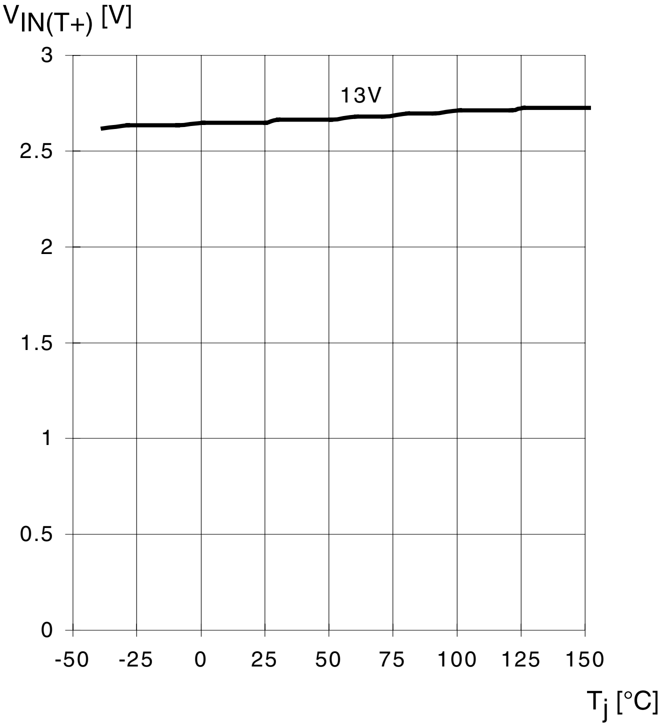
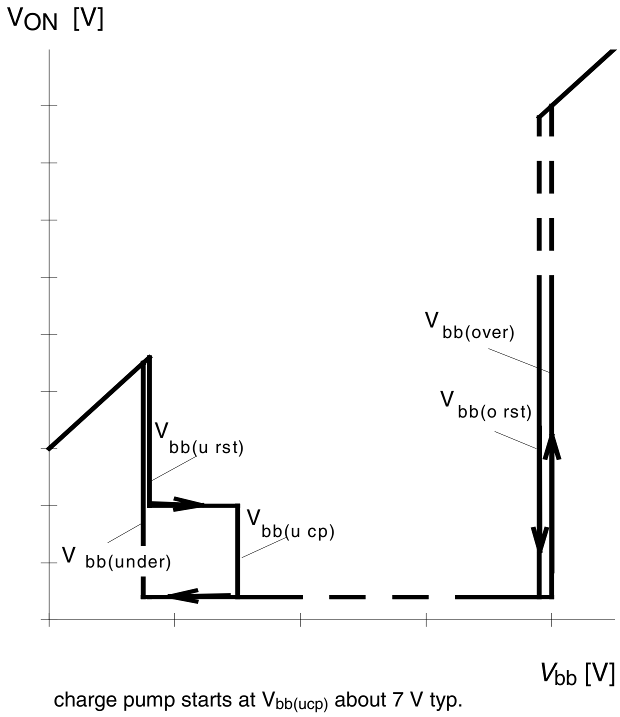
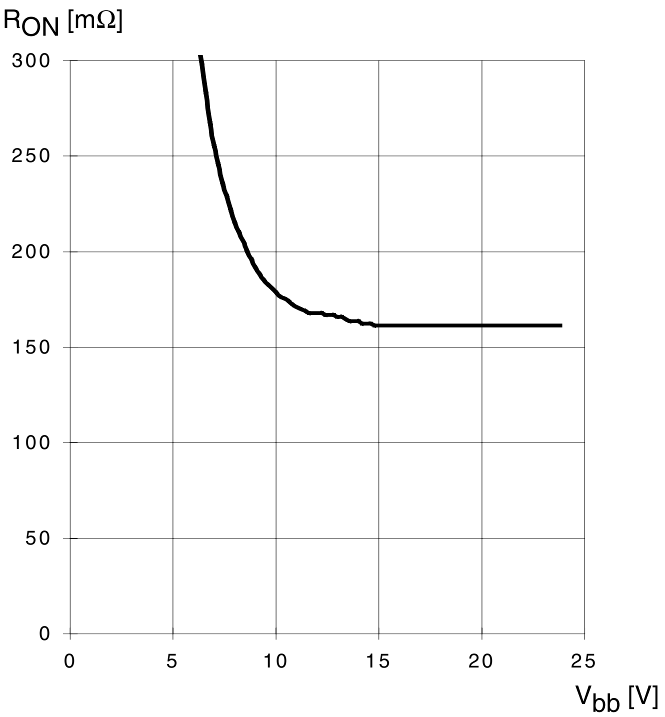


Figure 6: Undervoltage restart of charge pumpe

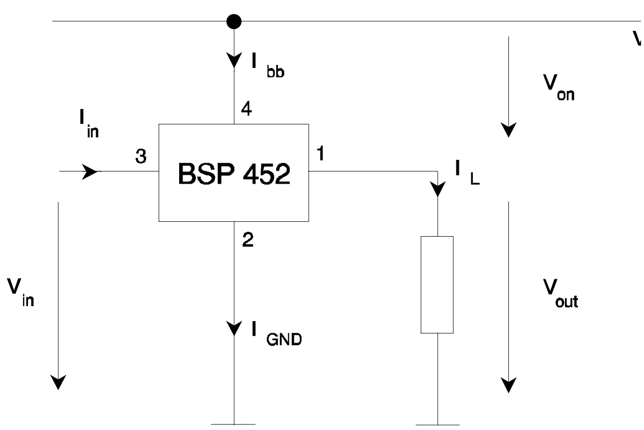


charge pump starts at $V_{bb(ucp)}$ about 7 V typ.

Typ. on-state resistance (Vbb-Pin to Out-Pin)
R_{ON} = f (V_{bb},I_L); I_L=0.5A, T_j = 25°C



Test circuit



Package Outlines

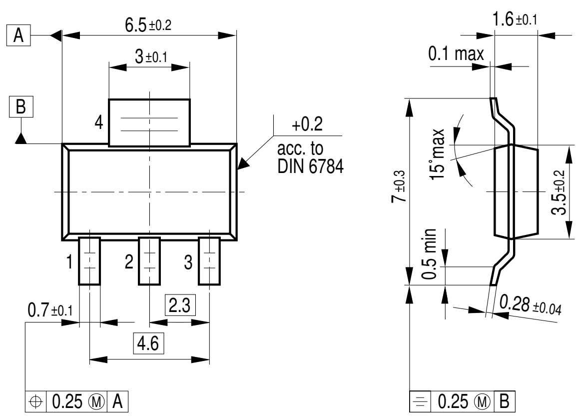


Figure 1 **PG-SOT-223** (Plastic Dual Small Outline Package) (RoHS-compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

Please specify the package needed (e.g. green package) when placing an order

You can find all of our packages, sorts of packing and others in our Infineon Internet Page "Products": **http://www.infineon.com/products**.

Dimensions in mm

Revision History

Version	Date	Changes
1.0	2007-05-25	Creation of the green datasheet. First page : Adding the green logo and the AEC qualified Adding the bullet AEC qualified and the RoHS compliant features Package page Modification of the package to be green.

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